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**MANIPAL INSTITUTE OF TECHNOLOGY**

MANIPAL

(A constituent unit of MAHE, Manipal)

**VII SEMESTER B.TECH. (MECHATRONICS ENGINEERING)**

**END SEMESTER EXAMINATIONS - MAKE UP**

**SUBJECT: MICRO ELECTRO MECHANICAL SYSTEM [MTE 4102]**

**DEC 2019/ JAN 2010**

Time: 3 Hours

MAX. MARKS: 50

**Instructions to Candidates:**

- ❖ Answer **ALL** the questions.
- ❖ Data not provided may be suitably assumed

- |            |  |          |            |
|------------|--|----------|------------|
| <b>1A.</b> | Distinguish between various actuation techniques used in microsystem   | <b>4</b> | <b>CO1</b> |
| <b>1B.</b> | Suggest a suitable solution for effective heat dissipation in microsystem and explain with a neat sketch   | <b>3</b> | <b>CO1</b> |
| <b>1C.</b> | With the help of schematic arrangement explain the process used for applying photoresist onto the surface of substrates.   | <b>3</b> | <b>CO4</b> |
| <b>2A</b>  | Differentiate Bio sensor and Bio-medical sensor. Explain their working principle with examples   | <b>5</b> | <b>CO1</b> |
| <b>2B</b>  | Estimate the associated changes in the acceleration (a), time (t) and power supply (P) to actuate a MEMS component when electrostatic force is reduced by a factor of 8  | <b>2</b> | <b>CO2</b> |
| <b>2C</b>  | Describe various mechanical problems associated with surface micromachining.   | <b>3</b> | <b>CO4</b> |
| <b>3A</b>  | Compare isotropic and anisotropic etching  | <b>3</b> | <b>CO4</b> |
| <b>3B</b>  | With the help of graphical illustration, describe the fabrication process used to develop thin metallic films of 100 Å thick   | <b>4</b> | <b>CO4</b> |
| <b>3C</b>  | Explain any three types of surface bonding techniques used in MEMS.  | <b>3</b> | <b>CO1</b> |
| <b>4A</b>  | Suggest a method to produce pure silicon crystal. With the help of a neat sketch, explain its working principal in detail  | <b>4</b> | <b>CO3</b> |
| <b>4B</b>  | Determine the minimum thickness of the rectangular diaphragm of a micro pressure sensor made of Silicon with conditions: Plane area = $32 \times 10^4 \mu\text{m}^2$ ; a/b ratio = 2; $\alpha = 0.0277$ ; $\beta = 0.4974$ ; Applied pressure = 24 MPa; Yield strength of silicon = 7000 MPa; Young's modulus = 190 GPa and Poisson's ratio = 0.25. Also find maximum stress if rectangular diaphragm is replaced with square, | <b>4</b> | <b>CO1</b> |

ii) circular diaphragm of same plane area

- 4C** What are the major technical issues involved in the application of MEMS in biomedicine? **2** **CO2**
- 5A** Suggest a method to develop passivation layer over a silicon substrate? Explain the process with a sketch. **4** **CO4**
- 5B** Determine the required electric voltage for ejecting a droplet of ink from an inkjet printer head using PZT piezoelectric crystal as a pumping mechanism. The ejected ink will have a resolution of 250 dpi (dots per inch). The ink droplet is assumed to produce a dot with a film thickness of 750 nm on the paper. The geometry and dimension of the printer head is illustrated in Fig. 5B. Assume that the ink droplet takes a shape of a sphere and the inkwell is always re-filled after ejection. Piezoelectric coefficients of PZT is  $480 \times 10^{-12} \text{ m/V}$  **4** **CO3**

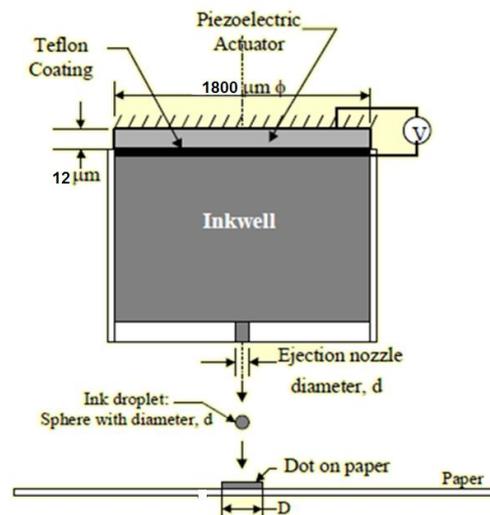


Fig. 5B Ink pumping mechanism in inkjet printer head

- 5C** Describe the different activities happen in a plasma generator **2** **CO1**